WISN

1. INTRODUCTION

MLCC consists of a conducting material and electrodes. To manufacture a chip-type SMT and achieve miniaturization, high density and high efficiency, ceramic condensers are used.

0201 MLCC is performed by high precision technology achieve high capacitance in unit size and ensure the stability and reliability of products.

2. FEATURES

- b. High capacitance in unit size.
- c. High precision dimensional tolerances.
- d. Suitable used in high-accuracy automatic mounting machine.

3. APPLICATIONS

- a. Miniature microwave module.
- b. Portable equipments (ex. Mobile phone, PDA).
- c. High frequency circuits.

4. HOW TO ORDER

<u>0201</u>	<u>N</u>	<u>100</u>	<u>J</u>	<u>250</u>	L	Ī
Size	Dielectric	<u>Capacitance</u>	<u>Tolerance</u>	Rated voltage	<u>Termination</u>	Packaging
Inch (mm)	N=NP0	Two significant digits	B =±0.1pF	Two significant digits	L=Ag/Ni/Sn (for NP0	T=7" reeled
0201 (0603)	(C0G)	followed by no. of zeros.	C =±0.25pF	followed by no. of	dielectric)	
	B =X7R	And R is in place of	D =±0.5pF	zeros. And R is in	C =Cu/Ni/Sn (for X7R,	
	X =X5R	decimal point.	G =±2%	place of decimal point.	X5R, Y5V dielectric)	
	F=Y5V		J =±5%			
		eg.:	K =±10%	4R0=4 VDC		
		R47=4.7pF	M=±20%	6R3=6.3 VDC		
		0R5=0.5pF	Z =-20/+80%	100=10 VDC		
		1R0=1.0pF		160=16 VDC		
		100=10x10 ⁰		250=25 VDC		
		=10pF				



5. EXTERNAL DIMENSIONS

Size Inch (mm)	L (mm)	W (mm)	T (mm)/Symbol		M _B (mm)
0201 (0603)	0.60±0.03	0.30±0.03	0.30±0.03	L	0.15±0.05
* Reflow soldering	g only.				



6. GENERAL ELECTRICAL DATA

Size	0201			
Dielectric	NP0 X7R		X5R	Y5V
Capacitance*	0.5pF to 100pF	100pF to 4.7nF	100pF to 10nF	22nF to 100nF
Capacitance tolerance	Cap≤5pF: C (±0.25pF) 5pF <cap<10pf: (±0.5pf)<br="" d="">Cap≥10pF: J (±5%)</cap<10pf:>	K (±10%)	K (±10%), M (±20%)	Z (-20/+80%)
Rated voltage (WVDC)	16V, 25V	10V, 16V	10V, 16V	4V, 6.3V
Tan δ / Q*	Cap<30pF, Q≥400+20C Cap≥30pF, Q≥1000	≤3.5% ≤5.0%		6.3V: ≤16% 4V: ≤20%
Insulation resistance at Ur	≥10GΩ	≥10GΩ or RxC≥500ΩxF whichever is less		er is less
Operating temperature	-55 to +125℃		-55 to +85℃	-25 to +85℃
Capacitance change	apacitance change ±30ppm		±15% +30	
Termination	Ni/Sn (lead-free termination)			

* Measured at 30~70% related humidity.

NP0: Apply 1.0±0.2Vrms, 1.0MHz±10% at the condition of 25 °C ambient temperature.

X7R, X5R: Apply 1.0±0.2Vrms, 1.0kHz±10% at the condition of 25 °C ambient temperature.

Y5V: Apply 1.0±0.2Vrms, 1.0kHz±10% at the condition of 20 °C ambient temperature.



7. CAPACITANCE RANGE

SIZE		02	01	
DIELECTRIC		NP0		
R	RATED VOLTAGE (VDC)		25	
	0.5pF (0R5)		L	
	1.0pF (1R0)		L	
	1.2pF (1R2)		L	
	1.5pF (1R5)		L	
	1.8pF (1R8)		L	
	2.2pF (2R2)		L	
	2.7pF (2R7)		L	
	3.3pF (3R3)		L	
	3.9pF (3R9)		L	
	4.7pF (4R7)		L	
	5.6pF (5R6)		L	
Capacitance	6.8pF (6R8)		L	
	8.2pF (8R2)		L	
	10pF (100)		L	
	12pF (120)		L	
	15pF (150)		L	
	18pF (180)		L	
	22pF (220)		L	
	27pF (270)		L	
	33pF (330)		L	
	39pF (390)		L	
	47pF (470)		L	
	56pF (560)	L	L	
	68pF (680)	L	L	
	82pF (820)	L	L	
	100pF (101)	L	L	

SIZE		0201					
DIELECTRIC		X7R	X5R		Y5V		
RATED VOLTAGE (VDC)		16V	10V	16V	4V	6.3V	
	100pF (101)	L					
	120pF (121)	L					
	150pF (151)	L					
	180pF (181)	L					
	220pF (221)	L					
	270pF (271)	L					
	330pF (331)	L					
	390pF (391)	L					
	470pF (471)	L					
	560pF (561)	L					
e	680pF (681)	L					
tan	820pF (821)	L					
acit	1,000pF (102)	L					
ap	1,500pF (152)	L		L			
0	2,200pF (222)	L		L			
	3,300pF (332)	L		L			
	4,700pF (472)	L		L			
	6,800pF (682)		L				
	0.010µF (103)		L				
	0.015µF (153)						
	0.022µF (223)					L	
	0.033µF (333)						
	0.047µF (473)					L	
	0.068µF (683)						
	0.10µF (104)				L		

1. The letter in cell is expressed the symbol of product thickness.

8. PACKAGING DIMENSION AND QUANTITY

Size	Thickness (mm)/Symbol		Paper tape		
5120			7" reel	13" reel	
0201 (0603)	0.30±0.03	L	15K	-	

Unit: pieces



APPENDIXES

Constructions

No.	Na	NP0	
1	Ceramic material		BaTiO₃ based
2	Inner electrode		AgPd alloy
3		Inner layer	
4	Termination	Middle layer	Ni
5		Outer layer	Sn



Storage and handling conditions

- (1) To store products at 5 to 40°C ambient temperature and 20 to 70%. related humidity conditions.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

Cautions:

- a. Don't store products in a corrosive environment such as sulfide, chloride gas, or acid. It may cause oxidization of electrode, which easily be resulted in poor soldering.
- b. To store products on the shelf and avoid exposure to moisture.
- c. Don't expose products to excessive shock, vibration, direct sunlight and so on.

Recommended soldering conditions

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of N_2 within oven are recommended.



